

SOT1001-1

plastic thermal enhanced very thin quad flat package; no leads; 36 terminals; resin based; body 5.5 x 4.5 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN36R
Package type industry code	HVQFN36R
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	R (resin based)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-11-2007

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.4	-	4.5	4.6	mm
E	package width	5.4	-	5.5	5.6	mm
A	seated height	[tbd]	-	0.85	0.9	mm
A ₂	package height	[tbd]	-	0.85	[tbd]	mm
n ₂	actual quantity of termination	-	-	36	-	

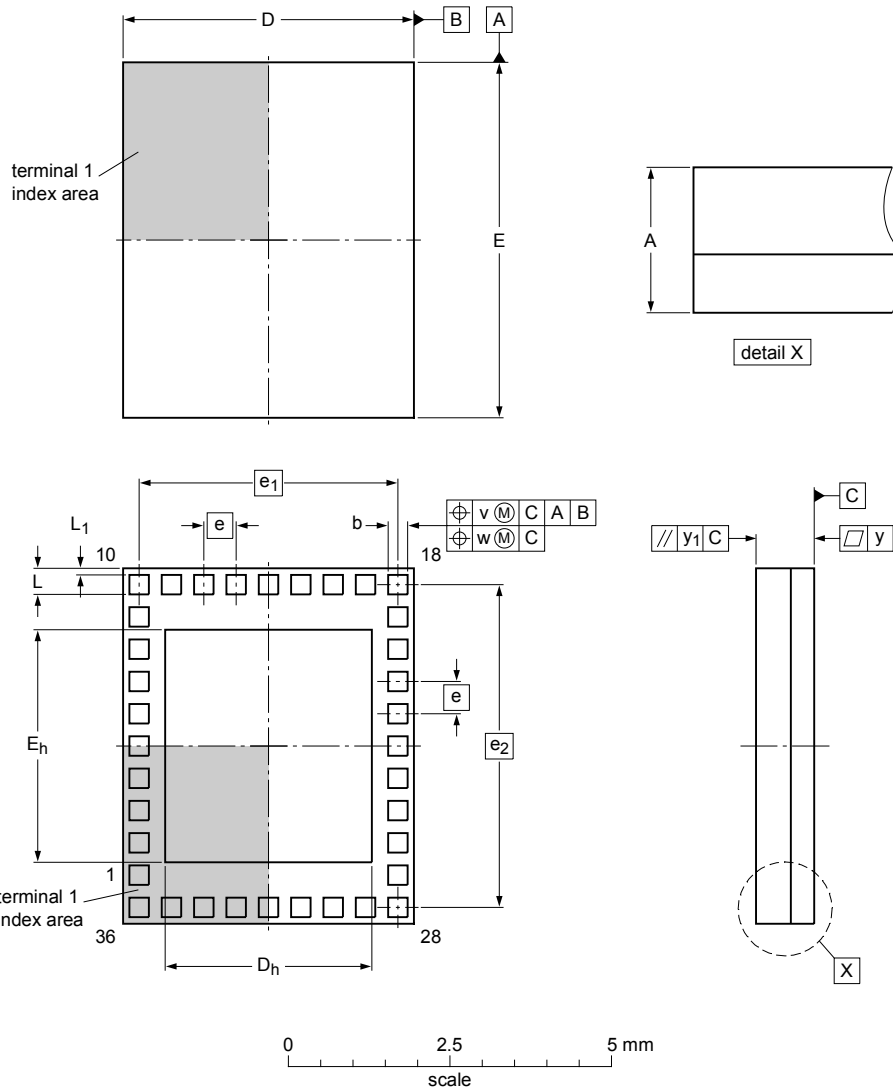


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2. Package outline

HVQFN36R: plastic thermal enhanced very thin quad flat package; no leads; 36 terminals; resin based; body 5.5 x 4.5 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A _{max}	b	D	D _h	E	E _h	e	e ₁	e ₂	L	L ₁	v	w	y	y ₁
mm	0.9	0.35 0.25	4.6 4.4	3.25 3.15	5.6 5.4	3.65 3.55	0.5	4	5	0.45 0.35	0.15 0.05	0.05	0.05	0.08	0.08

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT1001-1		---	---			07-06-21 07-11-14

Fig. 1. Package outline HVQFN36R (SOT1001-1)

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3. Legal information

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